

Title (en)

INTEGRATED ELECTRONIC MICROMODULE AND METHOD FOR MAKING SAME

Title (de)

ELEKTRONISCHER INTEGRIERTER MIKROMODUL UND HERSTELLUNGSVERFAHREN EINES SOLCHEN MIKROMODULS

Title (fr)

MICROMODULE ELECTRONIQUE INTEGRE ET PROCEDE DE FABRICATION D'UN TEL MICROMODULE

Publication

**EP 1097479 A1 20010509 (FR)**

Application

**EP 99925077 A 19990614**

Priority

- FR 9901405 W 19990614
- FR 9808426 A 19980629

Abstract (en)

[origin: FR2780551A1] Electronic micro modules (30) are produced by forming via holes (36-38) in an insulation layer (33, 34) for connecting flat coils (31) to buried chips. Simultaneous production of several electronic micro modules (30), involves: (a) mounting several chips (1) on a wafer (2); (b) depositing a blanket insulation layer (33, 34); (c) forming insulation layer holes (36-38) at the locations of the chip connection pads (4); (d) forming flat coil windings (31) on the support plate; (e) connecting each coil to a corresponding chip; and (f) dicing the plate to individualize the micro modules. Independent claims are also included for the following: (i) an electronic micro module with a chip buried in an insulating layer, on which a coil is provided; and (ii) a hybrid micro module having the above micro module on its back face.

IPC 1-7

**H01L 23/64**

IPC 8 full level

**H01L 25/00** (2006.01); **G06K 19/077** (2006.01); **H01L 23/498** (2006.01); **H01L 23/64** (2006.01); **H04B 5/00** (2006.01)

CPC (source: EP US)

**G06K 19/07747** (2013.01 - EP US); **G06K 19/07749** (2013.01 - EP US); **G06K 19/0775** (2013.01 - EP US); **H01L 23/49855** (2013.01 - EP US); **H01L 23/645** (2013.01 - EP US); **H01L 24/19** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H04B 5/263** (2024.01 - EP US); **H01L 2223/6677** (2013.01 - EP US); **H01L 2224/04105** (2013.01 - EP US); **H01L 2224/18** (2013.01 - US); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/45147** (2013.01 - US); **H01L 2224/73267** (2013.01 - EP US); **H01L 2224/92244** (2013.01 - EP); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01046** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/10253** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/19042** (2013.01 - EP US); **H01L 2924/30105** (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Citation (search report)

See references of WO 0001013A1

Designated contracting state (EPC)

CH DE ES FR GB IT LI NL

DOCDB simple family (publication)

**FR 2780551 A1 19991231**; **FR 2780551 B1 20010907**; AU 4268799 A 20000117; CN 100342536 C 20071010; CN 1315056 A 20010926; EP 1097479 A1 20010509; JP 2002519866 A 20020702; US 6319827 B1 20011120; WO 0001013 A1 20000106

DOCDB simple family (application)

**FR 9808426 A 19980629**; AU 4268799 A 19990614; CN 99810095 A 19990614; EP 99925077 A 19990614; FR 9901405 W 19990614; JP 2000557500 A 19990614; US 72070101 A 20010301